



STB70NF3LL

N-channel 30V - 0.0075Ω - 70A - D²PAK
Low gate charge STripFET™ II Power MOSFET

General features

Type	V _{DSS}	R _{DS(on)}	I _D
STB70NF3LL	30V	< 0.0095Ω	70A

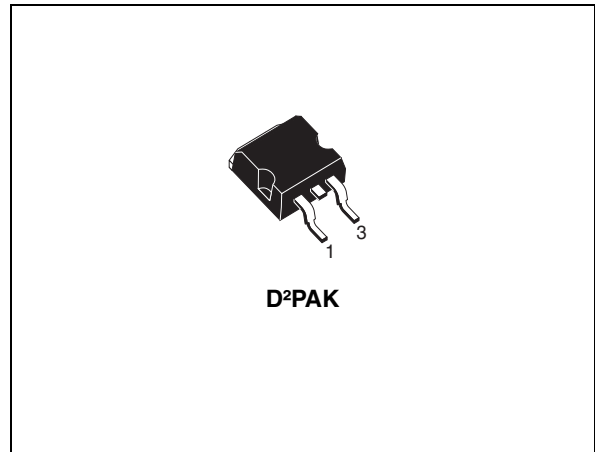
- Optimal R_{DS(on)} x Q_g trade-off @ 4.5V
- Conduction losses reduced
- Switching losses reduced

Description

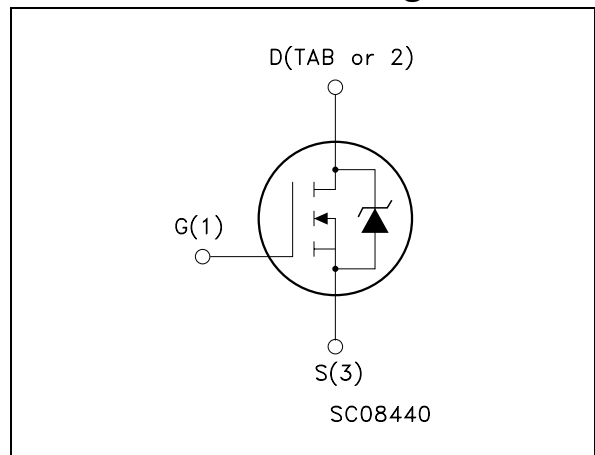
This application specific Power MOSFET is the third generation of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

Applications

- Switching application



Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STB70NF3LLT4	B70NF3LL @	D ² PAK	Tape & reel

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1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	30	V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20\text{ k}\Omega$)	30	V
V_{GS}	Gate- source voltage	± 16	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	70	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	50	A
$I_{DM}^{(2)}$	Drain current (pulsed)	280	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	100	W
	Derating factor	0.67	W/ $^\circ\text{C}$
$dv/dt^{(3)}$	Peak diode recovery voltage slope	5.5	V/ns
$E_{AS}^{(4)}$	Single pulse avalanche energy	500	mJ
T_{stg}	Storage temperature	-55 to 175	$^\circ\text{C}$
T_J	Operating junction temperature		

1. Current limited by the package
2. Pulse width limited by safe operating area
3. $I_{SD} \leq 0\text{A}$, $di/dt \leq 50\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq T_{JMAX}$
4. Starting $T_J = 25^\circ\text{C}$, $I_D = 35\text{A}$, $V_{DD} = 25\text{V}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case Max	1.5	$^\circ\text{C}/\text{W}$
R_{thJA}	Thermal resistance junction-ambient Max	62.5	$^\circ\text{C}/\text{W}$
T_l	Maximum lead temperature for soldering purpose	300	$^\circ\text{C}$

2 Electrical characteristics

($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0$	30			V
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ $T_C = 125^{\circ}\text{C}$			1 10	μA μA
I_{GSS}	Gate-body leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 16\ \text{V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ $I_D = 250\ \mu\text{A}$	1			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{V}$ $I_D = 35\text{A}$ $V_{GS} = 4.5\text{V}$ $I_D = 18\text{A}$		0.0075 0.010	0.0095 0.012	Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
g_{fs}	Forward Transconductance	$V_{DS} = 15\text{V}$ $I_D = 35\text{A}$		25		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25\text{V}$ $f = 1\text{MHz}$ $V_{GS} = 0$		1650 540 130		pF pF pF

Table 5. Switching times

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	$V_{DD} = 15V$ $I_D = 35A$ $R_G = 4.7\Omega$ $V_{GS} = 4.5V$ (Resistive Load Figure 16)		23 165		ns ns
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 15V$ $I_D = 70A$ $V_{GS} = 4.5V$		24 8.5 12	33	nC nC nC
$t_{d(off)}$ t_f	Turn-off delay time Fall time	$V_{DD} = 15V$ $I_D = 35A$ $R_G = 4.7\Omega$ $V_{GS} = 4.5V$ (Resistive Load Figure 16)		27 28		ns ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)				70 280	A A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 70A$ $V_{GS} = 0$			1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 70A$ $di/dt = 100A/\mu s$ $V_{DD} = 20V$ $T_J = 150^\circ C$ (see test circuit Figure 14)		42 52 2.5		ns nC A

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

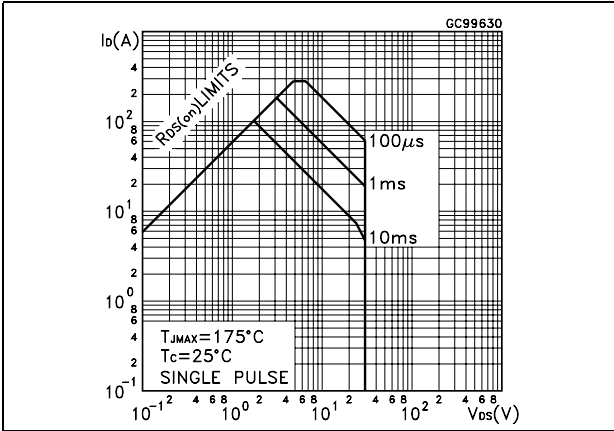


Figure 2. Thermal impedance

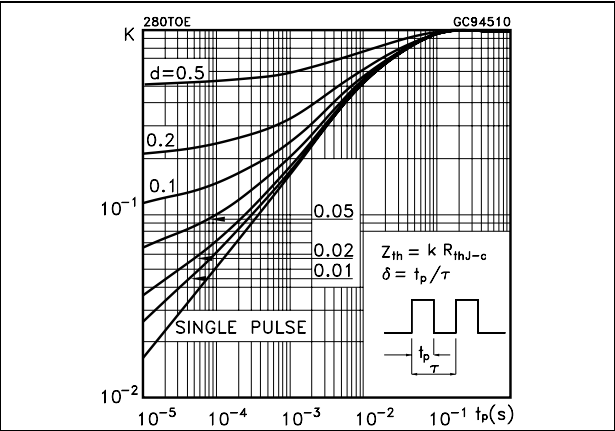


Figure 3. Output characteristics

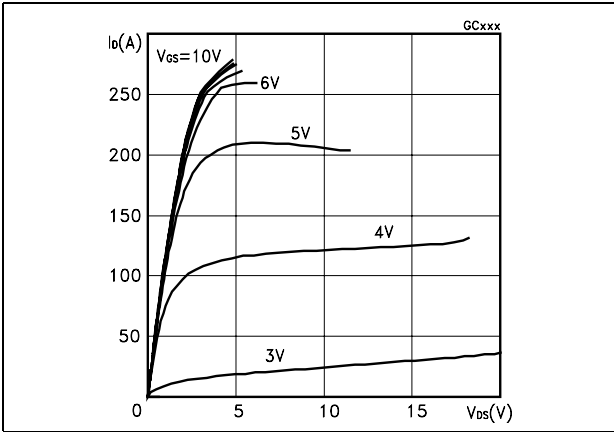


Figure 4. Transfer characteristics

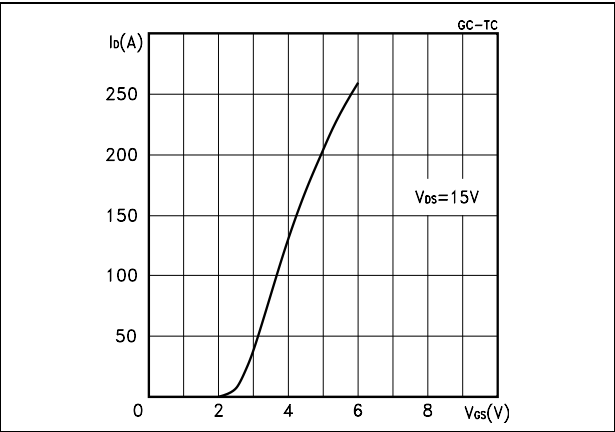


Figure 5. Source-drain diode forward characteristics

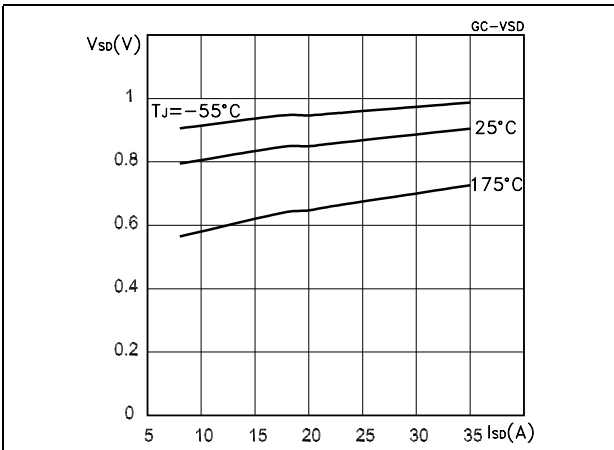


Figure 6. Static drain-source on resistance

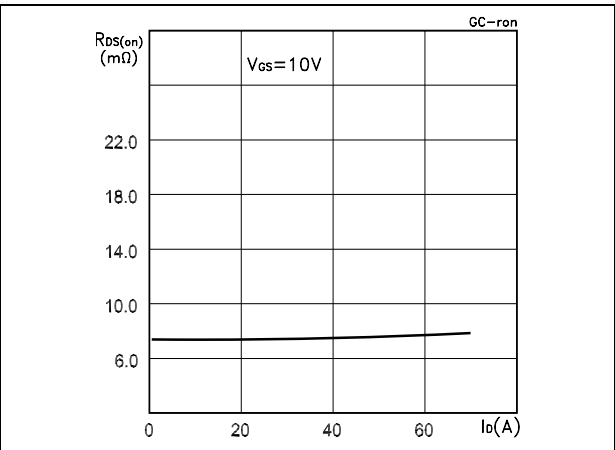


Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

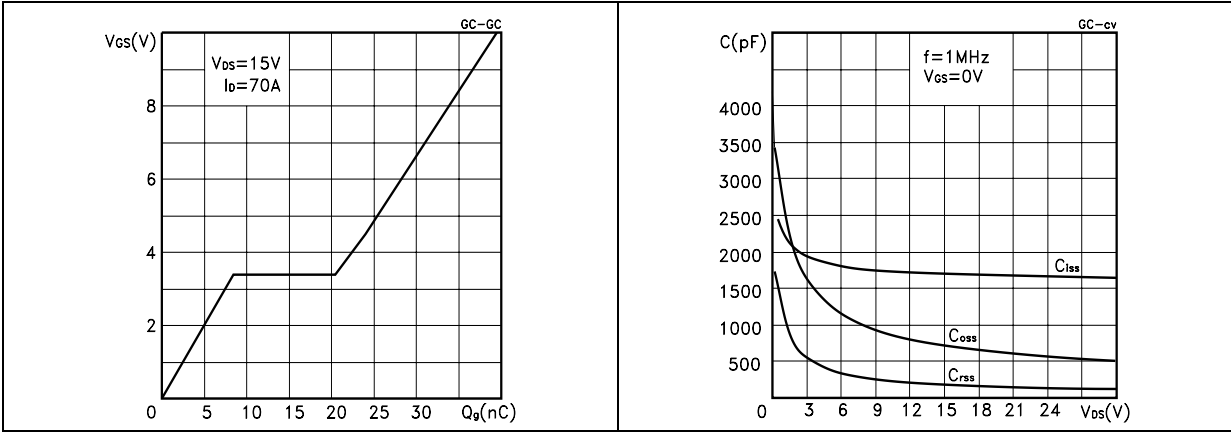


Figure 9. Normalized gate threshold voltage vs temperature Figure 10. Normalized on resistance vs temperature

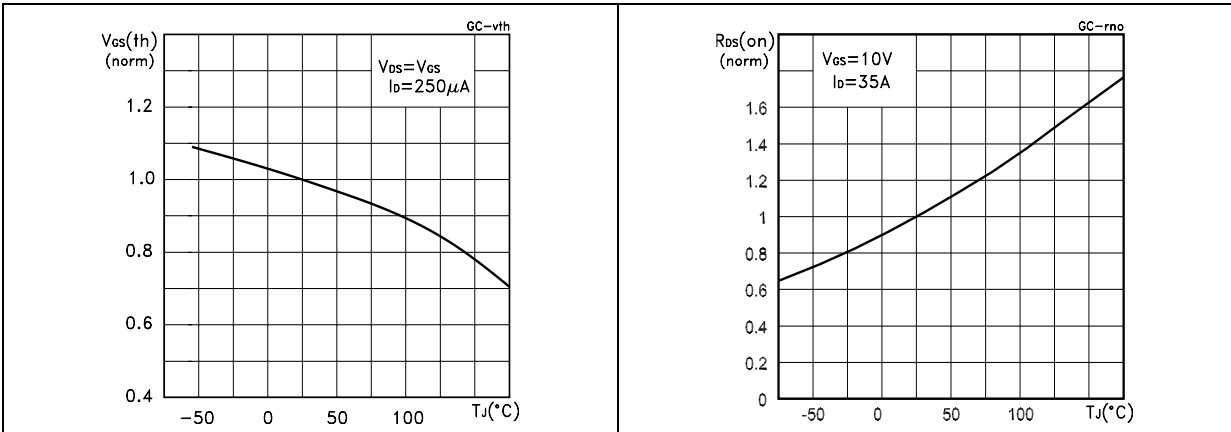
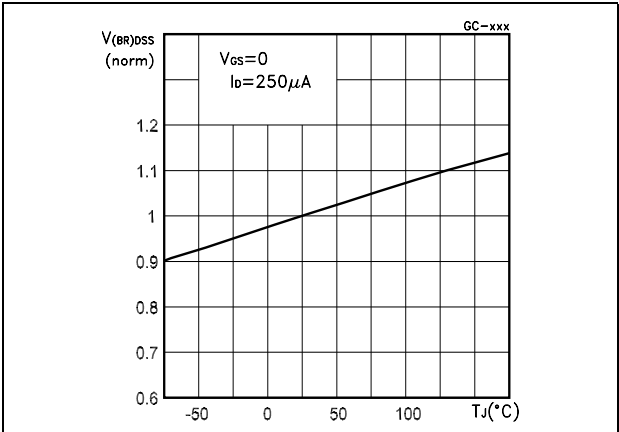


Figure 11. Normalized breakdown vs temperature



3 Test circuit

Figure 12. Switching times test circuit for resistive load

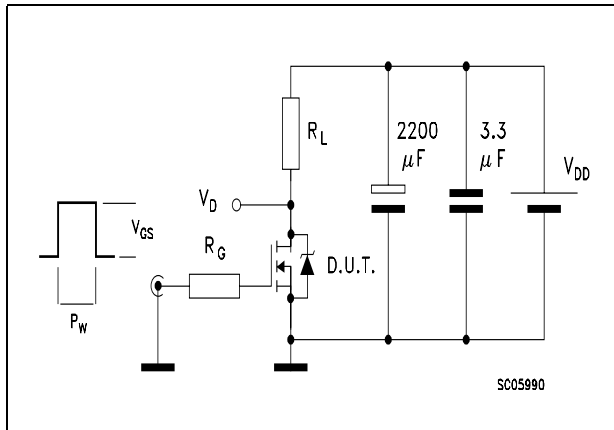


Figure 13. Gate charge test circuit

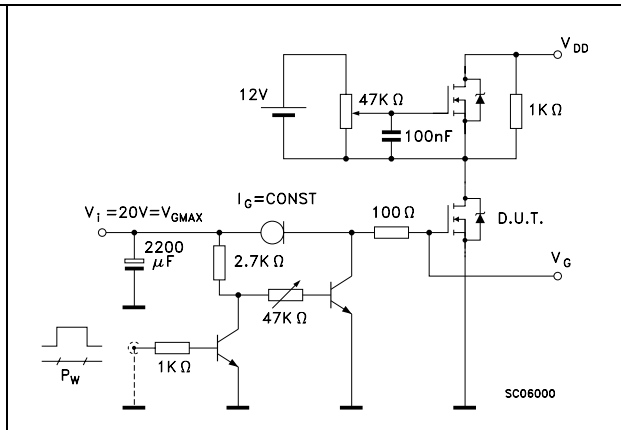


Figure 14. Test circuit for inductive load switching and diode recovery times

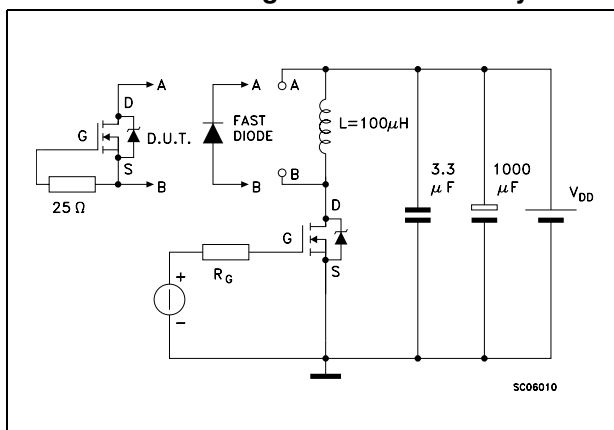


Figure 15. Unclamped Inductive load test circuit

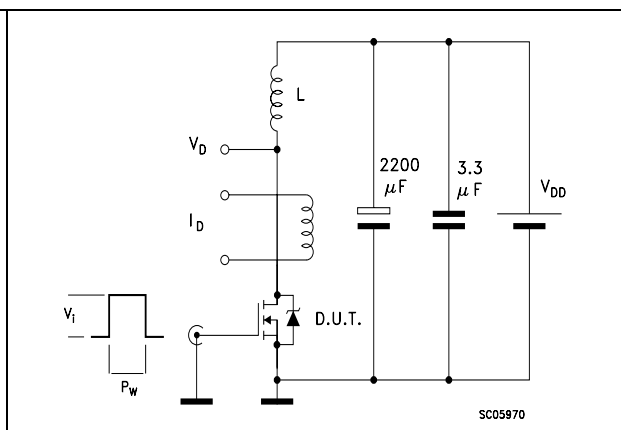
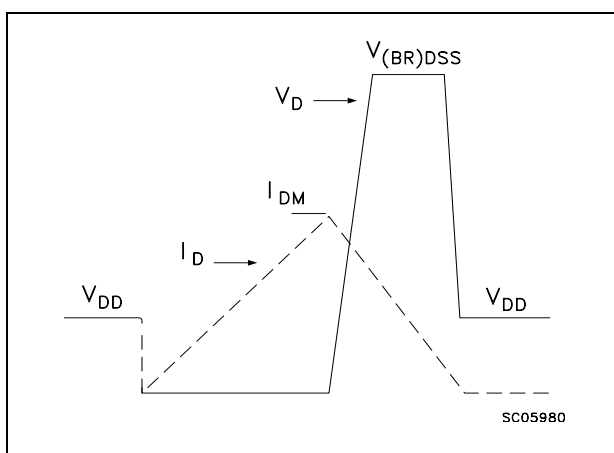


Figure 16. Unclamped inductive waveform

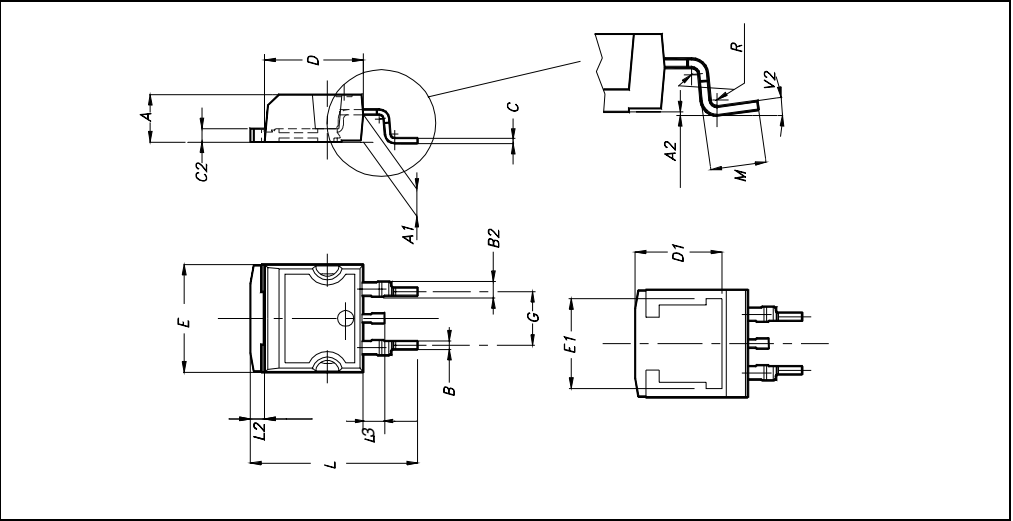


4 **Package mechanical data**

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

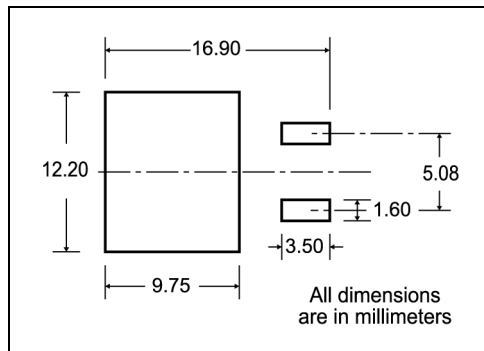
D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		4°			

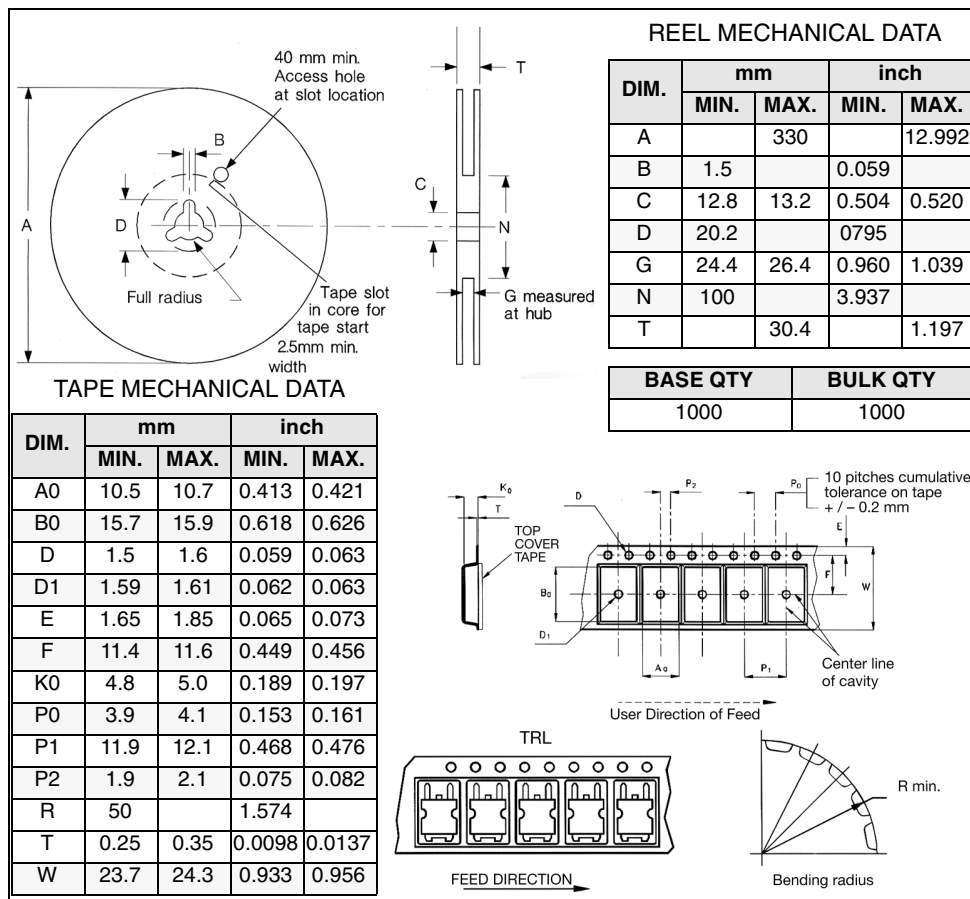


5 Packing mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT



* on sales type

6 Revision history

Table 7. Revision history

Date	Revision	Changes
21-Jun-2004	6	Preliminary version
25-Jul-2006	7	New template, no content change

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